

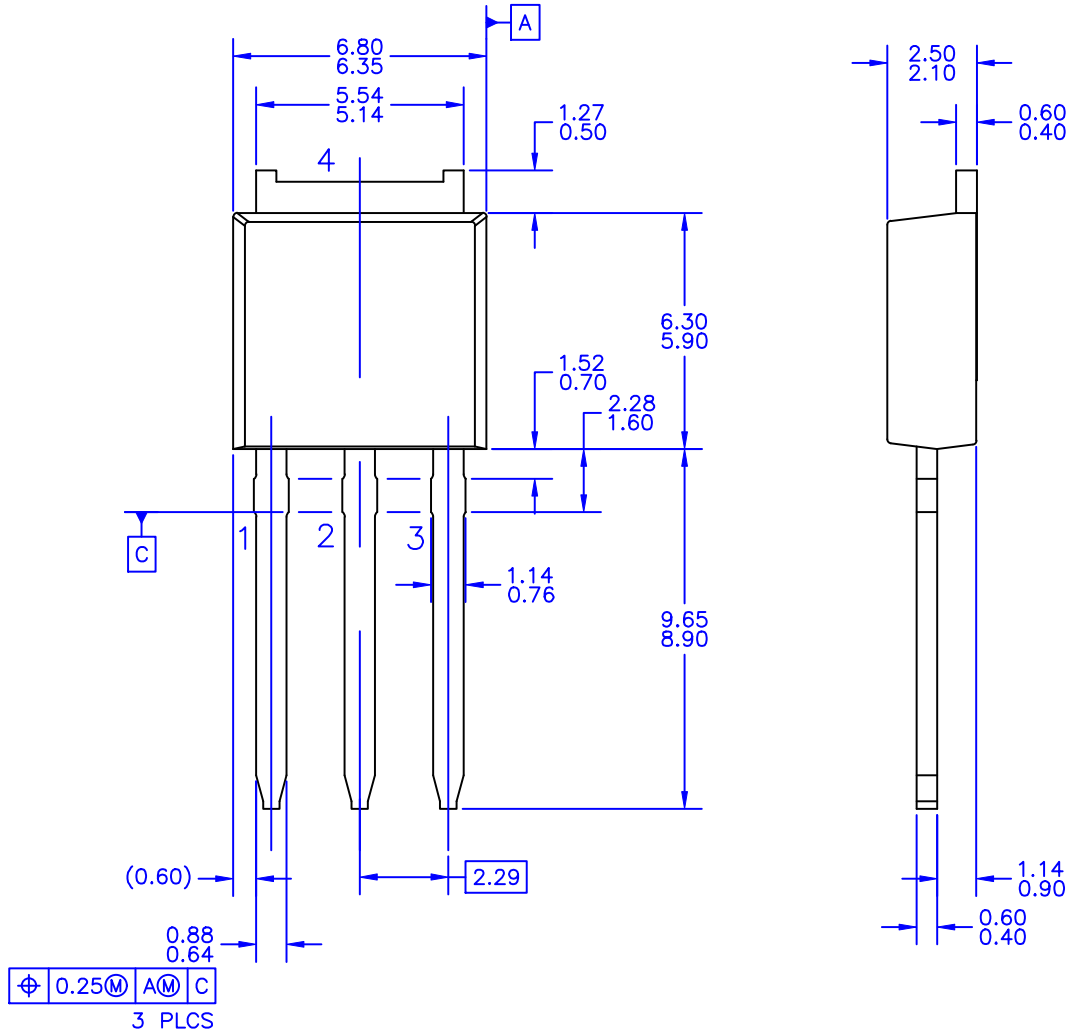
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

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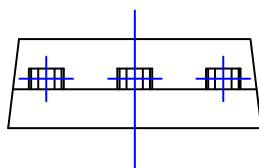
**DPAK3 (IPAK)**  
**CASE 369AR**  
**ISSUE O**

DATE 30 SEP 2016



NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
- B) THIS PACKAGE CONFORMS TO JEDEC, TO-251, ISSUE C, VARIATION AA, DATED SEP 1988.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.



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